

🌐 Peru 📅 August 20-22, 2025

CONFERENCE WEBSITE: <https://intercon.org.pe/papers.html>

| About the Conference

The 2025 IEEE XXXII International Conference on Electronics, Electrical Engineering and Computing – INTERCON 2025 -- Index SCOPUS

Abbreviation : INTERCON 2025

Perú, Arequipa| August 20 to 22, 2025

Website: <https://intercon.org.pe/>

The 2025 IEEE XXXII International Conference on Electronics, Electrical Engineering and Computing – INTERCON aims to bring together researchers, professionals, students, and entrepreneurs to foster collaboration, address global challenges, and promote the development of technologies that benefit humanity.

INTERCON is a prestigious IEEE technical conference organized by the IEEE Peru Section, recognized for its commitment to innovation and excellence in engineering and computing.

The 2025 edition will be held in person in the city of Arequipa, Peru, and will be co-organized by the

Important Dates

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20**

CONFERENCE
DATE
**August 20-
22, 2025**

Universidad Católica Santa María (UCSM) and its IEEE UCSM Student Branch. This year's theme draws inspiration from the IEEE Future Directions platforms, with a focus on transformative and emerging technologies.

We warmly invite you to submit your technical papers for oral, on-site presentations. INTERCON 2025 will continue its tradition of providing a vibrant and dynamic platform for knowledge exchange, research dissemination, and collaboration between academia, industry, and innovators—further advancing IEEE's mission to foster technology for the benefit of humanity.

■ Important Dates

Full Paper Submission Deadline (Last Call): June 15

Notification of Acceptance: July 1

Camera-Ready Submission: July 20

Author Registration Deadline: July 20

Oral Presentations: August 20-22

■ Submission Guidelines

The official language of INTERCON 2025 is ENGLISH. The maximum number of authors per paper, including co-authors, is six (6). Papers must be submitted in PDF format and be between six (6) and eight (8) pages long, following the <https://www.ieee.org/conferences/publishing/templates>

We will use EasyChair system for submissions

here: [https://easychair.org/conferences/?](https://easychair.org/conferences/?conf=intercon2025)

[conf=intercon2025](https://easychair.org/conferences/?conf=intercon2025)

Accepted papers must be presented on-site to be eligible for submission to the IEEE Xplore Digital Library.

▣ List of Topics

T1. Artificial Intelligence and Machine Learning

T2. Communications and Networking

T3. Power, Energy, and Power Electronics

T4. Biomedical Engineering & Healthcare Technologies

T5. Robotics, Control, Instrumentation, and Automation

T6. Multimedia Signal Processing and Analytics

T7. Devices, Circuits, and Materials

T8. Data Science and Computing Technologies

T9. Education in Engineering and Technology

▣ Venue

The conference will be held in person at Universidad Católica Santa María (UCSM), in the city of Arequipa, Peru.

▣ Contact

All questions about submissions should be emailed to intercon@ieee.org.pe

TOPICS OF INTEREST

3 topics

Research papers are invited in, but not limited to, the following areas:

Computer Science & Software Engineering

Electrical & Electronics Engineering

Uncategorized

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